

Dual N-Channel MOSFET

AO4948 (KO4948)

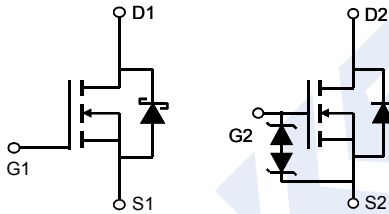
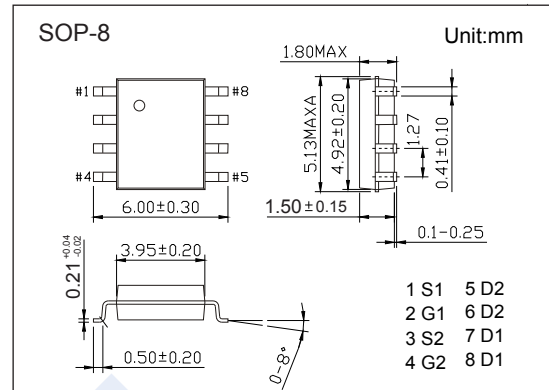
■ Features

N-Channel 1

- $V_{DS} (V) = 30V$
- $I_D = 8.8 A (V_{GS} = 10V)$
- $R_{DS(ON)} < 16m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} < 22m\Omega (V_{GS} = 4.5V)$
- SRFET™ Soft Recovery MOSFET: Integrated Schottky Diode

N-Channel 2

- $V_{DS} (V) = 30V$
- $I_D = 8 A (V_{GS} = 10V)$
- $R_{DS(ON)} < 19m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} < 28m\Omega (V_{GS} = 4.5V)$
- ESD Rating: 2KV HBM

■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	N-Channel 1	N-Channel 2	Unit	
Drain-Source Voltage	V_{DS}	30		V	
Gate-Source Voltage	V_{GS}	± 20			
Continuous Drain Current	I_D	$T_A=25^\circ C$	8.8	A	
		$T_A=70^\circ C$	7.1		
Pulsed Drain Current	I_{DM}	60	40	mJ	
Avalanche Current	I_{AS}, I_{AR}	21	13		
Repetitive Avalanche Energy	$L=0.3mH$	E_{AS}, E_{AR}	66	25	
Power Dissipation	P_D	$T_A=25^\circ C$	2		W
		$T_A=70^\circ C$	1.3		
Thermal Resistance.Junction- to-Ambient	R_{thJA}	$t \leq 10s$	62.5		$^\circ C/W$
		Steady-State	90		
Thermal Resistance.Junction- to-Lead	R_{thJL}	40		$^\circ C$	
Junction Temperature	T_J	150			
Storage Temperature Range	T_{stg}	-55 to 150			

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■ N-Channel 1 Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Drain-Source Breakdown Voltage	V _{DSS}	I _D =250μA, V _{GS} =0V	30			V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			0.1	mA	
		V _{DS} =30V, V _{GS} =0V, T _J =55°C			20		
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.1		2.2	V	
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =8.8A			16	mΩ	
		V _{GS} =10V, I _D =8.8A, T _J =125°C			25		
		V _{GS} =4.5V, I _D =7A			22		
On State Drain Current	I _{D(ON)}	V _{GS} =10V, V _{DS} =5V	60			A	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =8.8A		29		S	
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =15V, f=1MHz		1267	1600	pF	
Output Capacitance	C _{oss}			308			
Reverse Transfer Capacitance	C _{rss}			118			
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V, f=1MHz		1.3	2	Ω	
Total Gate Charge (10V)	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =8.8A		21	30	nC	
Total Gate Charge (4.5V)				10.4			
Gate Source Charge			Q _{gs}		3		
Gate Drain Charge			Q _{gd}		3.6		
Turn-On DelayTime	t _{d(on)}	V _{GS} =10V, V _{DS} =15V, R _L =1.7Ω, R _{GEN} =3Ω		5.2		ns	
Turn-On Rise Time	t _r			3.8			
Turn-Off DelayTime	t _{d(off)}			21.2			
Turn-Off Fall Time	t _f			4.4			
Body Diode Reverse Recovery Time	t _{rr}	I _F = 8.8A, di/dt= 300A/us		11.2	15	nC	
Body Diode Reverse Recovery Charge	Q _{rr}			10.5			
Maximum Body-Diode Continuous Current	I _S				3.5	A	
Diode Forward Voltage	V _{SD}	I _S =1A, V _{GS} =0V			0.5	V	

Note. The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.

■ Marking

Marking	4948
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Dual N-Channel MOSFET

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■ N-Channel 2 Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DSS}	I _D =250 μA, V _{GS} =0V	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	μA
		V _{DS} =30V, V _{GS} =0V, T _J =55°C			5	
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±16V			±10	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2		2.4	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =8A			19	mΩ
		V _{GS} =10V, I _D =8A, T _J =125°C			25	
		V _{GS} =4.5V, I _D =4A			28	
On State Drain Current	I _{D(ON)}	V _{GS} =10V, V _{DS} =5V	40			A
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =8A		30		S
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =15V, f=1MHz	600		888	pF
Output Capacitance	C _{oss}		77		145	
Reverse Transfer Capacitance	C _{rss}		50		115	
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V, f=1MHz	0.5		1.7	Ω
Total Gate Charge (10V)	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =8A	12		18	nC
Total Gate Charge (4.5V)			6		9	
Gate Source Charge			Q _{gs}	2		
Gate Drain Charge	Q _{gd}		2		5	
Turn-On DelayTime	t _{d(on)}	V _{GS} =10V, V _{DS} =15V, R _L =1.8Ω, R _{GEN} =3Ω		5		ns
Turn-On Rise Time	t _r			3.5		
Turn-Off DelayTime	t _{d(off)}			19		
Turn-Off Fall Time	t _f			3.5		
Body Diode Reverse Recovery Time	t _{rr}	I _F = 8A, di/dt= 500A/us	6		10	nC
Body Diode Reverse Recovery Charge	Q _{rr}		14		22	
Maximum Body-Diode Continuous Current	I _S				2.5	A
Diode Forward Voltage	V _{SD}	I _S =1A, V _{GS} =0V			1	V

Note. The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.

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■ N-Channel 1 Typical Characteristics

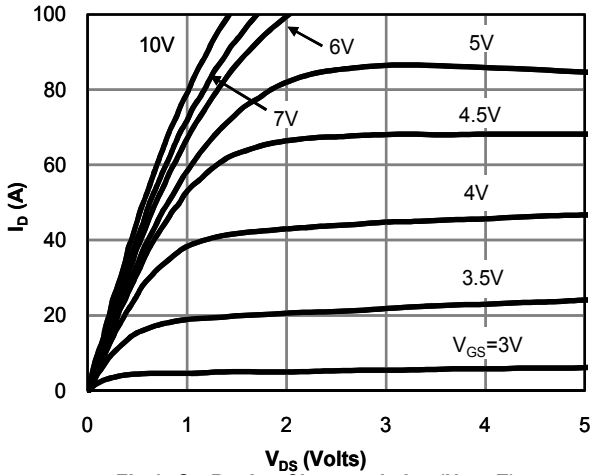


Fig 1: On-Region Characteristics (Note E)

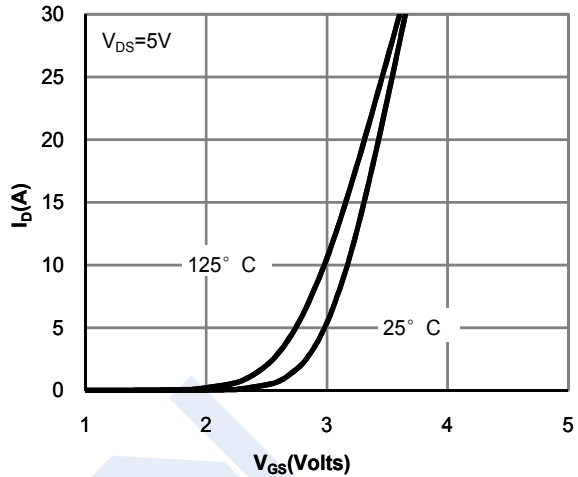


Figure 2: Transfer Characteristics (Note E)

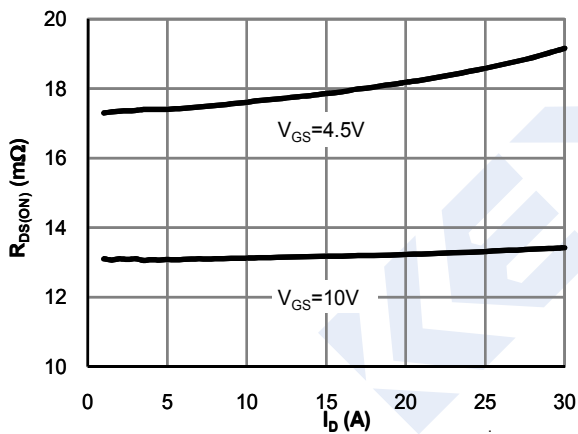


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

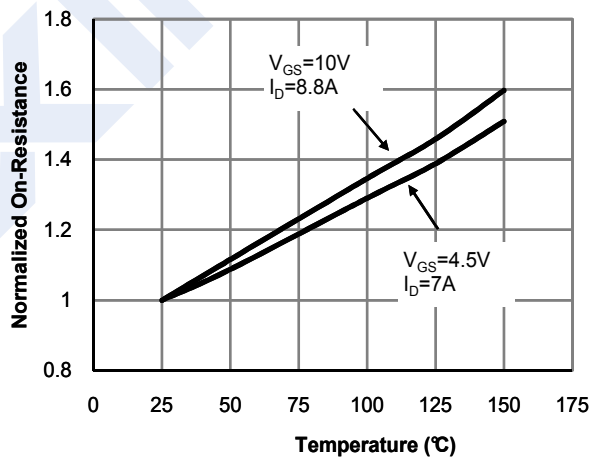


Figure 4: On-Resistance vs. Junction Temperature

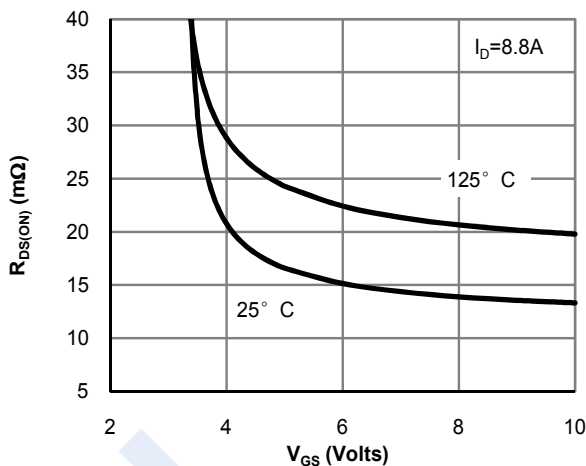


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

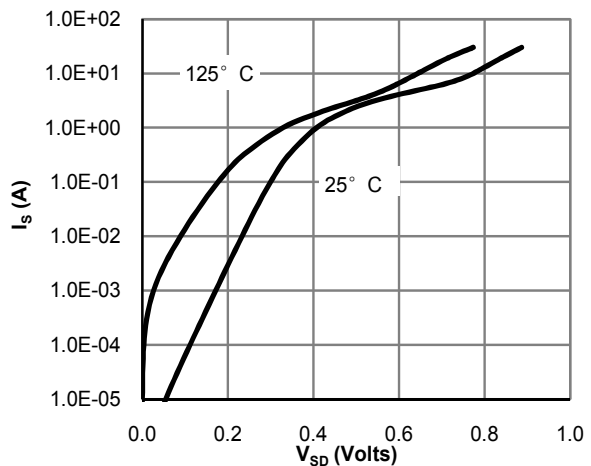


Figure 6: Body-Diode Characteristics (Note E)

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■ N-Channel 1 Typical Characteristics

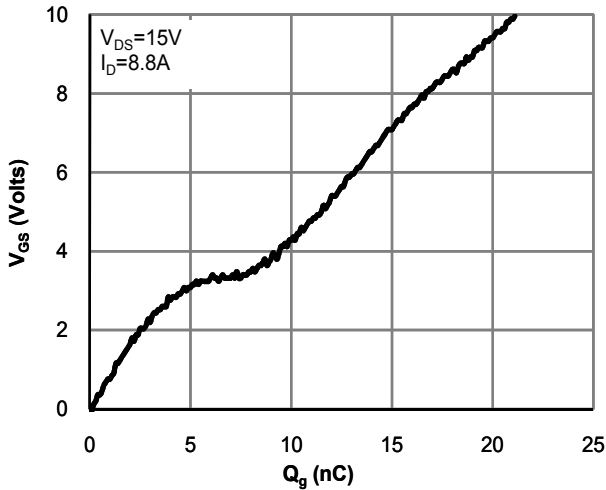


Figure 7: Gate-Charge Characteristics

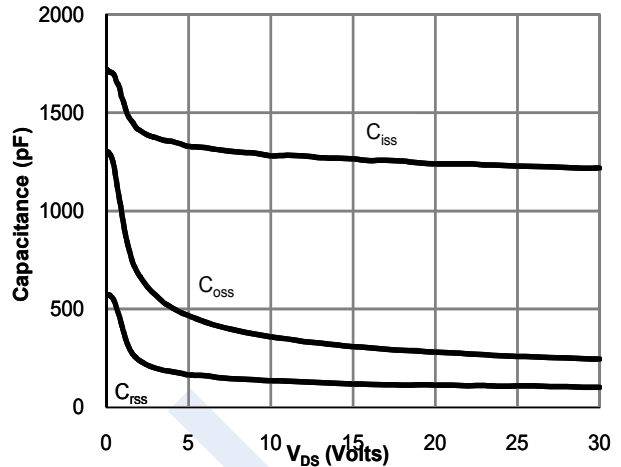


Figure 8: Capacitance Characteristics

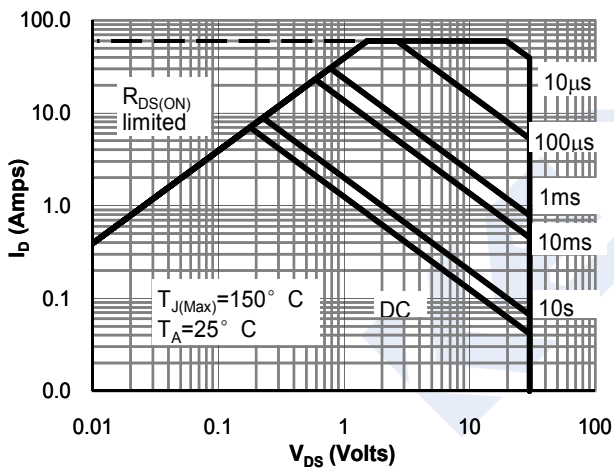


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

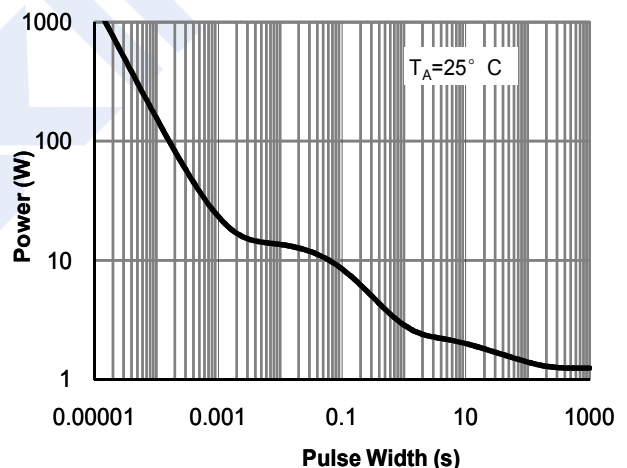


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

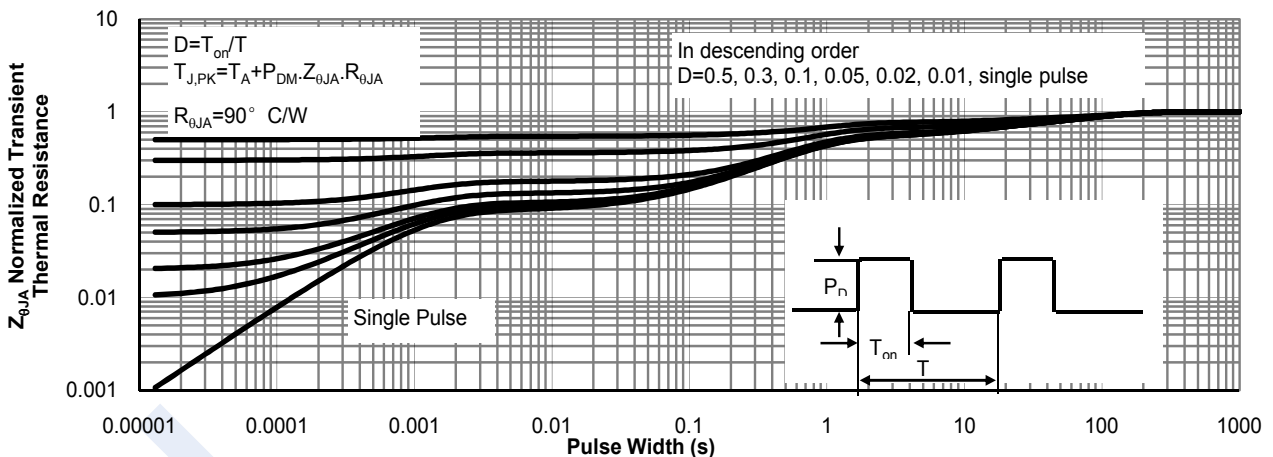


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

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■ N-Channel 2 Typical Characteristics

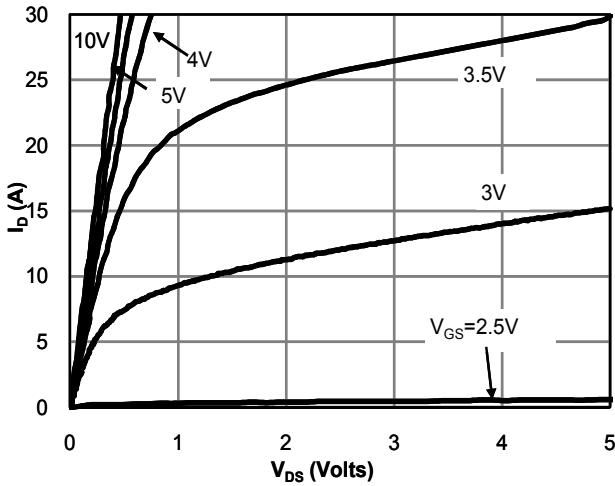


Fig 1: On-Region Characteristics (Note E)

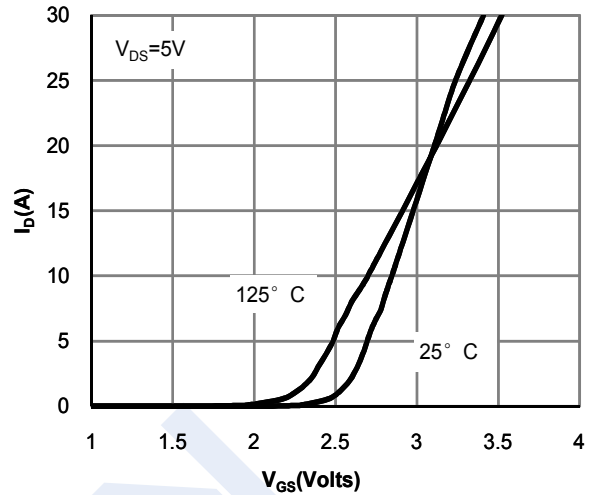


Figure 2: Transfer Characteristics (Note E)

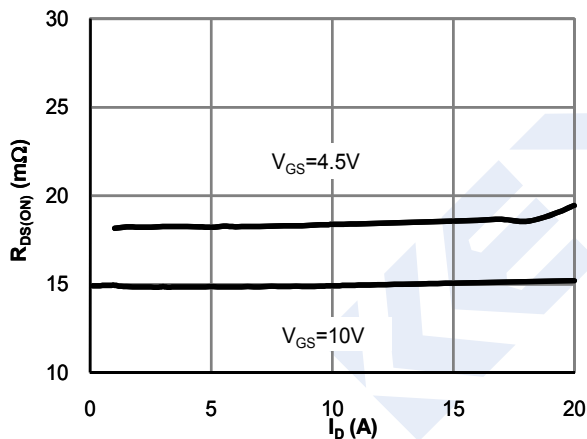


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

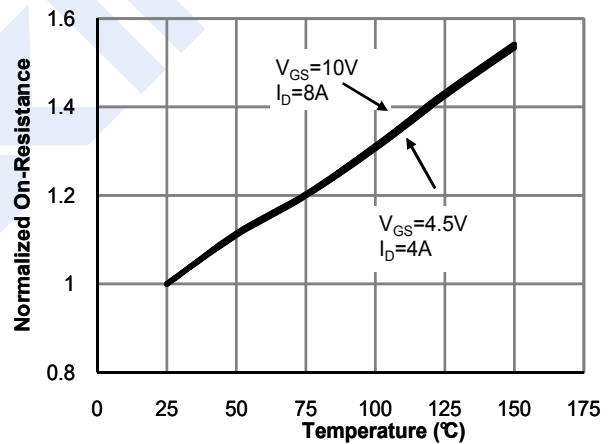


Figure 4: On-Resistance vs. Junction Temperature

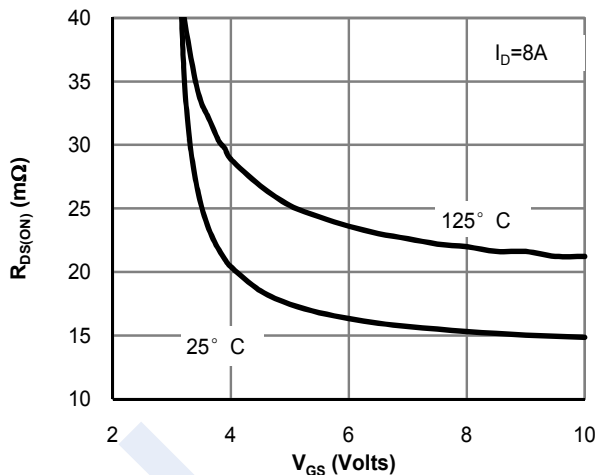


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

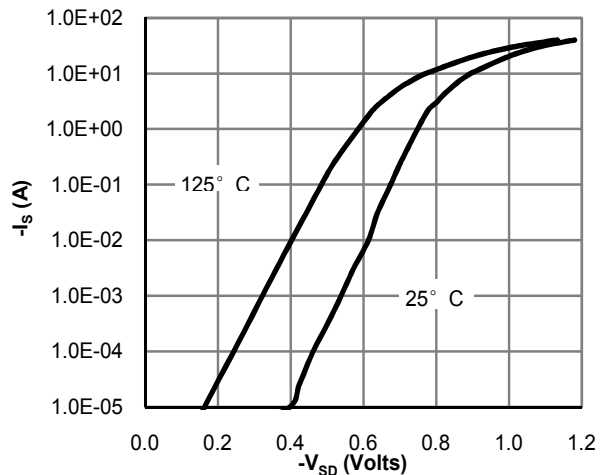


Figure 6: Body-Diode Characteristics (Note E)

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■ N-Channel 2 Typical Characteristics

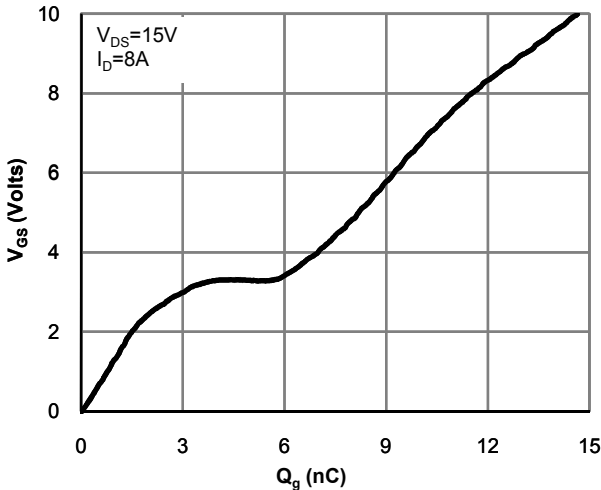


Figure 7: Gate-Charge Characteristics

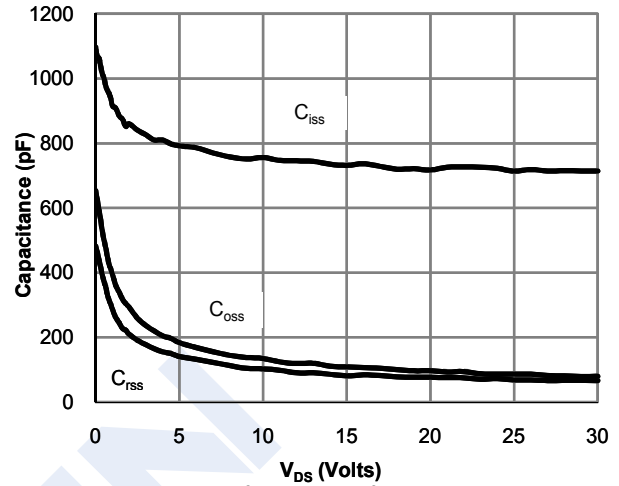


Figure 8: Capacitance Characteristics

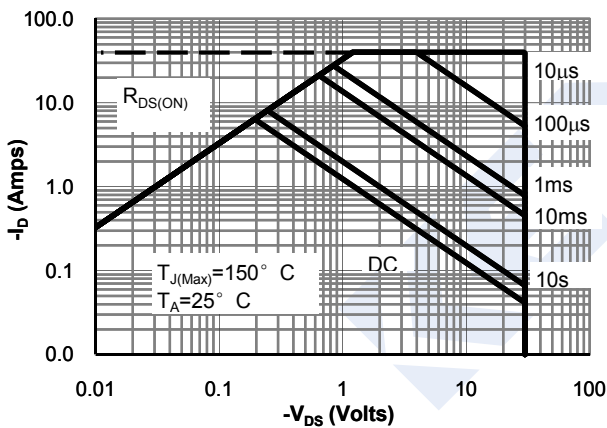


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

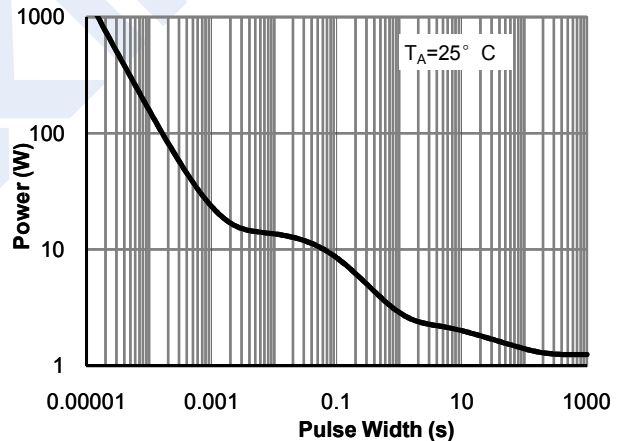


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

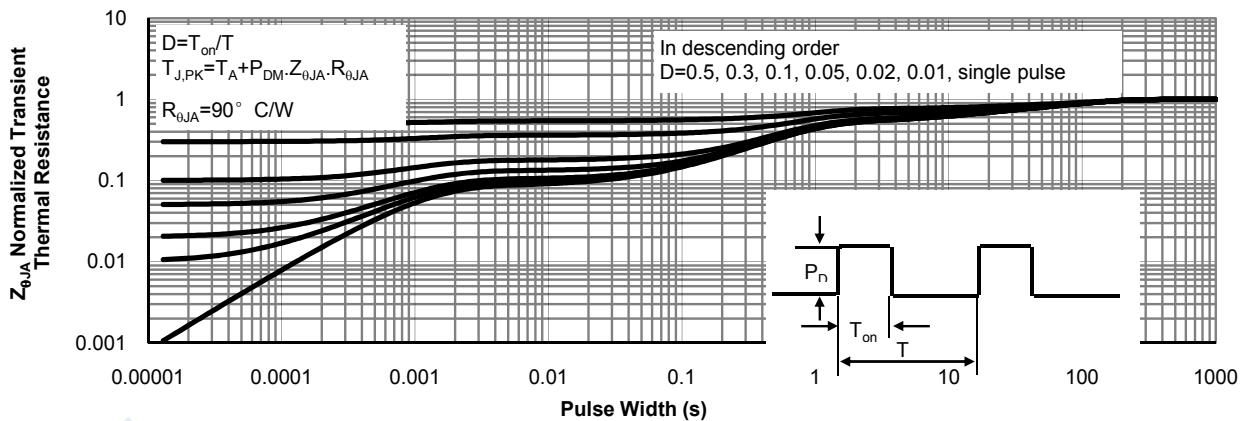


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)